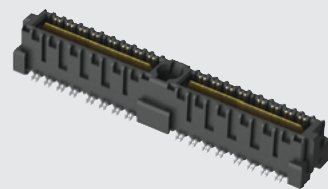


QMS-026-06.75-L-D-A



(0,635 mm) .025"

QMS SERIES

RUGGED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:

Liquid Crystal Polymer

Terminal & Ground

Plane Material:

Phosphor Bronze

Plating:

Au over 50µ" (1,27 µm) Ni

(Tin on Ground Plane Tail)

Current Rating:

Contact:

2.6 A per pin

(1 pin powered per row)

Ground Plane:

15.7 A per ground plane

(1 ground plane powered)

Voltage Rating:

300 VAC mated with QFS

Operating Temp:

-55°C to +125°C

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (026-052)

(0,15 mm) .006" max (078)

Board Stacking:

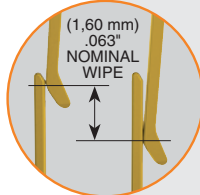
For applications requiring more than two connectors per board, contact ipg@samtec.com

Board Mates:

QFS

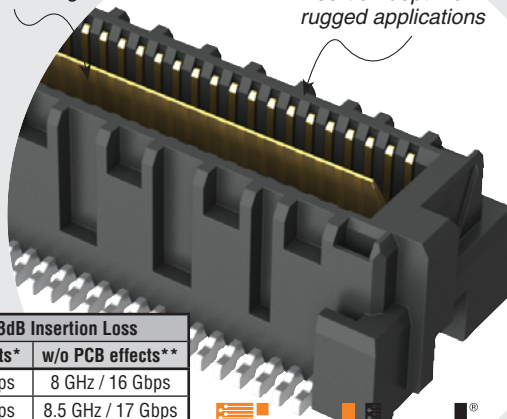
Cable Mates:

6QCD



Integral metal plane
for power or ground

Increased
insertion depth for
rugged applications



QMS/QFS 10 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	8 GHz / 16 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	7.5 GHz / 15 Gbps	9 GHz / 18 Gbps

*Performance data includes effects of a non-optimized PCB.

**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?QMS or contact sig@samtec.com

ALSO AVAILABLE (MOQ Required)

- Other platings
 - Guide Posts
 - Without PCB Alignment Pins (05.75 and 06.75 only)
 - Hot Pluggable
 - 64 (-DP) and 104 positions per row
- Contact Samtec.

Final **inch**
C E R T I F I E D

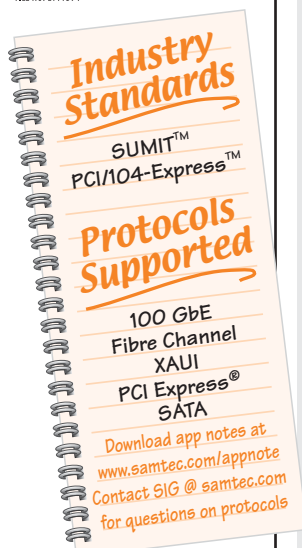
28+
Gbps

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594



Note: Some lengths, styles and options are non-standard, non-returnable.

QMS	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank = -D) -016, -032, -048 (16 pairs per bank = -D-DP) (-078 & -048 Not available with -09.75 lead style)	Specify LEAD STYLE from chart	-L (-05.75 and -06.75 lead style only) = 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails) -SL (-09.75 lead style only) = 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)	-D = Single-Ended -D-DP = Differential Pair	-K = (5,50 mm) .217" DIA Polyimide film Pick & Place Pad	APPLICATION Requires Standoff SO-1524-03-01-01-L for 15,24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

MATED HEIGHT*				
LEAD STYLE	A	QFS LEAD STYLE		
		-04.25	-06.25	
-05.75	(5,38) .212	10 mm	12 mm	
-06.75	(6,35) .250	11 mm	13 mm	
-09.75	(9,35) .368	14 mm	16 mm	

*Processing conditions will affect mated height.

(No. of Banks) x (21,34) .840 - (0,51) .020

(21,34) .840

(7,26) .286

(2,29) .090

(0,635) .025

(0,23) .009

(0,25) .010

(6,35) .250

(7,52) .296

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm